

HPF-18-01-T-S

HPF-10-02-T-S

**HPF SERIES**

(5,08 mm) .200"

# POWER SOCKETS

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HPF](http://www.samtec.com?HPF)

**Insulator Material:**

Black LCP

**Contact Material:**

BeCu

**Plating:**

Sn over

50µ" (1,27 µm) Ni

**Insertion Depth:**

(3,68 mm) .145" to (8,26 mm)

.325" (.368" (9,35 mm) plus

board thickness minimum for

bottom entry)

**Wiping Distance:**

(0,38 mm) .015"

**Insertion Force:**

(Single contact only)

56 oz (15,57 N) avg.

**Withdrawal Force:**

(Single contact only)

52 oz (14,46 N) avg.

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0,15 mm) .006" max (02-10)

(0,20 mm) .008" max (11-20)

**RoHS Compliant:**

Yes

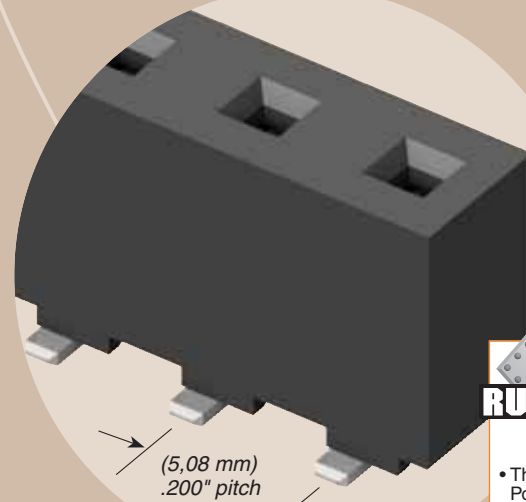
Mates with:  
HPM, HPW

**POWER EYE CONTACT**



HPF/HPM	
PINS	CURRENT RATING (PER CONTACT)
1	16.6 A
2	14.4 A
3	13.2 A
4	12.7 A
ALL	8.9 A

Surface Mount  
or  
Through-hole



(5,08 mm)  
.200" pitch

**RUGGEDIZED**  
by SAMTEC

- Three-finger Power Eye contact
- Locking clip option

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



HPF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	S	OTHER OPTIONS
	02 thru 20	-01 = Through-hole -02 = Surface Mount	-T = Matte Tin		-LC = Locking Clip (Manual placement required) (Style -02 only) -K = (6,50 mm) .256" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel Packaging (14 positions maximum) (Style -02 only)

Dimensional drawings showing:
 

- Top view: No. of Positions x (5,08) .200
- Side view: (2,59) .102, (8,89) .350, (0,46) .018, (2,46) .097, (1,14) .045
- Bottom view: (7,11) .280, -02
- Lead height: (9,35) .368

**Note:** Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)